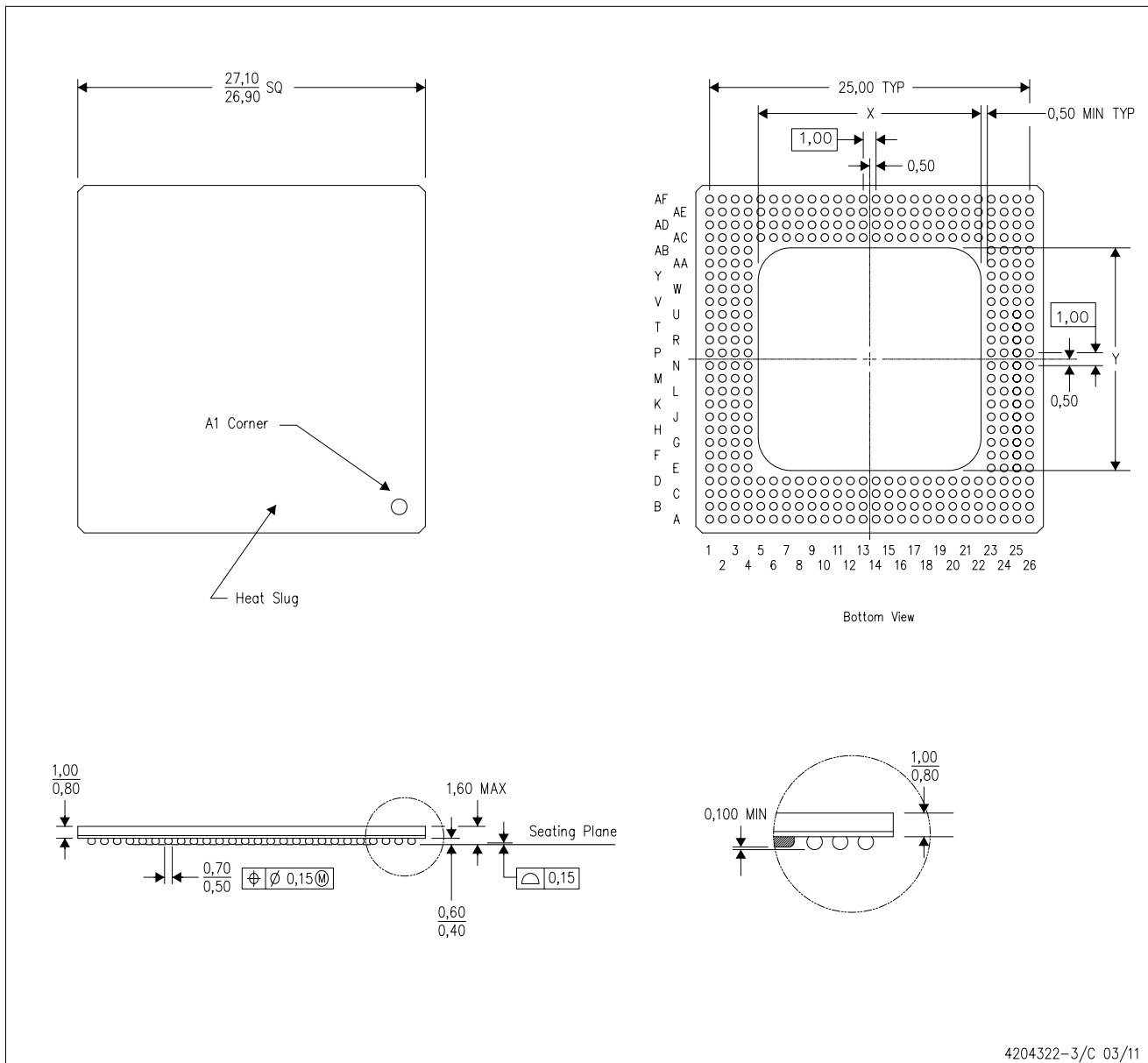


MECHANICAL DATA

ZND (S-PBGA-N352)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Thermally enhanced plastic package with heat slug (HSL).
 - The encapsulation size (X,Y) will vary with cavity size. The distance from bond finger edge to encapsulation shall be min 0.5mm
 - This is a Pb-free solder ball design.

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